

HIGHEST ACCURACY, HIGHEST UPH FLIP-CHIP PERFORMANCE

Kulicke & Soffa's **Katalyst**[™] delivers the industry's highest **accuracy** and **speed** for flip-chip placement. Its hardware and technology enable < 3 µm accuracy on substrate or wafer, achieving the best Cost-of-Ownership in the industry.

Advanced automation and software features have been employed to achieve exceptional Ease-of-use, allowing the Katalyst to act like a single-nozzle machine.

KEY FEATURES

- Dual Gantry with Multi-nozzle Placement
- Multi-die Pickup and Multi-die Dip Flux
- Industry Leading 15K UPH
- 50 µm Thin-die Pick Capability
- < 3 µm Accuracy</p>
- Single-nozzle Setup and Teach
- Machine Health Check Diagnostic
- Complete Material and Process Tracking

- Automated Accuracy Stability Feature
- Electronic Vibration Cancellation Feature
- In-situ Flux-dip Quality Inspection
- Fast Tool-less Application Changeover
- Automated Die Ejector, Pick Tool, and Place Tool Changers
- Industry 4.0 Compliant

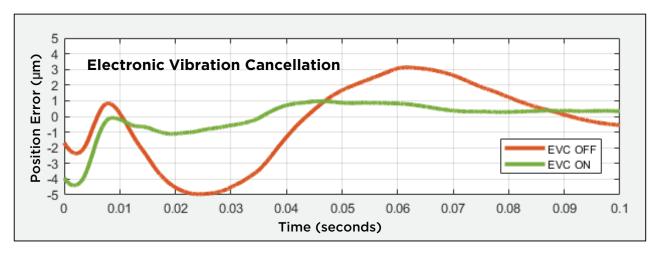




ELECTRONIC VIBRATION CANCELLATION

Katalyst delivers the industry's highest accuracy and throughput performance through the use of an Electronic Vibration Cancellation feature that measures and compensates for machine vibrations.





TECHNICAL SPECIFICATIONS

Typical Applications

BGA, QFN, eWLB, and WHA

Accuracy

< 3 μ m at 3 σ

Throughput

15K UPH (real production with 100 ms dip and bond times)

Die Size (8 or 12 inch Wafer)

1 - 15.5 mm (6 nozzles, 15K UPH)

16 - 30 mm (3 nozzles, 7K UPH)

Die Thickness

> 50 µm

Substrate Types

Carriers, boats, and bare substrates

Substrate Size

340 x 340 mm (bondable area 330 x 330 mm) Single, dual, and triple lanes indexing

Substrate / Carrier Thickness

0.1 - 6 mm

Bond Force

0.5 - 25 N

Tool Changers

Die Ejector, Pick Tool, and Place Tool Changers

Product Changeover Time

< 30 min changeover (fully automated)

Clean Room Class

1,000

Technology Innovation Solutions

For more information, contact your local authorized K&S sales representative or visit www.kns.com

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